# **3M Z-Axis Adhesive Film** 5303R

Technical Data		K	ebruary, 1999
Product Description	3M <sup>TM</sup> Z-Axis Adhesive Film 5303R is a heat- adhesive film. It is a non-tacky, heat and press adhesive matrix randomly loaded with conduc interconnection of circuit lines through the adl spaced far enough apart for the product to be of the adhesive.	ure cured system co ctive particles. These hesive thickness (the	nsisting of an particles allow e "Z-axis"), but are
General Information	3M film 5303 connects and mechanically bon copper/polyimide circuits – to a variety of elec including printed circuit boards, glass substrat Film 5303R is ideal for high performance syst interconnect resistance, with high stability and demanding environmental conditions, along w	ctronic substrates an es (LCD displays) a ems requiring low e l reliability over a w	d metallizations nd flex circuits. lectrical
	Film 5303R is supplied on a clean room compatible poly release liner for easy handling. The release liner is removed after the film has been heat tacked to one of the substrates to be bonded. The flex circuit and LCD or flex circuit and PCB are then aligned and a final bond is made using a hot bar bonder (see the Bonding section of this data page).		
	Design parameters for interconnecting circuit	lines with Film 5303	3R
	Note: The following technical information and o or typical only and should not be used for		
	Minimum free space (gap) between adjacent conductors to ensure electrical insulation	70 µm	2.75 mils
	Minimum conductor overlap area per conductor to ensure electrical connection in the Z-axis	0.0645 mm <sup>2</sup>	100 mils <sup>2</sup>

## **Z-Axis Adhesive Film**

5303R

#### **Typical Properties**

Note: The following technical information and data should be considered representative or typical only and should not be used for specification purposes.

Property	Value	Units
Adhesive Type	Cyanate Ester/ Thermoplastic Blend	
Liner Type	Polyester Film with Silicone release	
Adhesive Thickness	25 (1) and 50 (2)	micron (mil)
Liner Thickness	75 microns (3 mil)	
Dielectric Strength (AC, 1Hz - 105 Hz)	> 5	kV / mm
Dielectric Strength (DC)	> 8	kV / mm
Surface Resistivity	10 <sup>12</sup>	$\Omega$ / square
Modulus (cured)	> 109	Pascals
Coefficient of Thermal Expansion	100	ppm / °C
Moisture Absorption (85°C / 85% RH)	1.2	%
Ionic Content Chloride Sodium Potassium	< 5 < 5 < 20	ppm
Tacking Conditions Temperature* Pressure Time	80 - 100 0.7 (10) 2-5	°C Kg / cm² (psi) seconds
Bonding Conditions Temperature* Pressure Time	180 19.6 (280) 15-20	°C Kg / cm² (psi) seconds

\*Temperature measured in the adhesive. Thermode set points will be higher and will depend upon the substrate materials and bond equipment.

#### **Typical Performance**

Note: The following technical information and data should be considered representative or typical only and should not be used for specification purposes.

	Flex to PWB	Flex to ITO/Glass	
Interconnect Resistance (200 micron line width) (IPC TM650 2.6.24)	< 50 mΩ	< 1Ω	
Peel Strength	> 100 g/cm	> 1000 g/cm	
Shear Strength	> 70 Kg/cm <sup>2</sup>	> 70 Kg/cm <sup>2</sup>	

## Z-Axis Adhesive Film

5303R

Construction	<b>Rolls:</b> 3 mm wide x 50 meters long 3 mm wide x 10 meters long (other widths may be custom ordered and are subject to availability)		
	Sheet: 10 cm x 15 cm Custom sizes		
Thickness Optimization	3M film 5303R comes in two thicknesses to accommodate interconnect bonding substrates with different types of metallization. The 25 micron (1 mil) thickness is ideal when one or both substrates has a thin film metallization, eg. Indium tin oxide on ITO glass for an LCD to flex interconnection. The 50 micron (2 mil) thickness is recommended when the metallization on both substrates is thicker, e.g. PWB to flex interconnection.		
Bonding	Bonding of film 5303R requires a three part procedure: heat tacking the film to the flex circuit (or to the LCD, PCB etc.), removal of the release liner, and bonding the flex to the second substrate. Detailed bonding instructions are available in a Technical Service Bulletin, and these instructions must be followed to obtain good electrical and mechanical bonding.		
	A thermocompression (hot bar) bonder is required for use of film 5303R, and several commercially available models exist; a list of vendors can be obtained by calling the toll free number on the back of this Technical Data Sheet.		
Repair	Bonds made with film 5303R are repairable by heating the bondline (eg. with a hot plate or rework tool) peeling the substrates apart. The bond site then requires cleaning with a solvent (Methyl ethyl ketone recommended) and then the circuit can be rebonded using a fresh piece of film 5303R.		
	<b>Note:</b> Carefully read and follow manufacturer's precautions and directions for use when using cleaning solvents.		
Storage	3M 5303R should be kept frozen (-5°C/23°F) in the original metallized airtight shipping pouch. Prior to use, while still inside the shipping pouch, film 5303R should be allowed to warm to room temperature for approximately 30 minutes to prevent condensation on the film and possible adhesive cracking. Freezer stored materials have a shelf life of 12 months. Reels exposed to room temperature for more than 2 weeks accumulated time may exhibit handling problems such as cracking or flaking of the adhesive and separation of the adhesive from the liner. Sheets of film 5303R or lengths unwound from the reel may show this type of failure earlier. While in storage film 5303R should be kept away from direct sources of heat and light.		

### **Z-Axis Adhesive Film**

3M MAKES NO WARRANTIES, EXPRESS OR IMPLIED, INCLUDING, BUT NOT LIMITED TO, ANY
IMPLIED WARRANTY OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE. User is responsible for determining whether the 3M product is fit for a particular purpose and suitable for user's method of application. Please remember that many factors can affect the use and performance of a 3M product in a particular application. The materials to be bonded with the product, the surface preparation of those materials, the product selected for use, the conditions in which the product is used, and the time and environmental conditions in which the product. Given the variety of factors that can affect the use and performance of a 3M product. Given the variety of factors that can affect the use and performance of a 3M product. Given the variety of factors that can affect the use and performance of a 3M product to determine whether it is fit for a particular purpose and suitable for the user's method of application.
If the 3M product is proved to be defective, THE EXCLUSIVE REMEDY, AT 3M'S OPTION, SHALL BE TO REFUND THE PURCHASE PRICE OF OR TO REPAIR OR REPLACE THE DEFECTIVE 3M PRODUCT. 3M shall not otherwise be liable for loss or damages, whether direct, indirect, special, incidental, or consequential, regardless of the legal theory asserted, including negligence, warranty, or strict liability.



Bonding Systems Division 3M Center, Building 220-7E-01 St. Paul, MN 55144-1000

